



# SK3C0B

## Surface Mount Schottky Barrier Rectifier

### FEATURES

- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Meets environmental standard MIL-S-19500D
- Moisture sensitivity:level 1, per J-STD-020
- Solder dip 275 °C, 10 s
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC



DO-214AA ( SMB )

### TYPICAL APPLICATIONS

For use in general purpose rectification of lighting, power supplies, inverters, converters and freewheeling diodes for consumer, automotive and telecommunication.

PRIMARY CHARACTERISTICS	
I <sub>F(AV)</sub>	3 A
V <sub>RRM</sub>	200 V
I <sub>FSM</sub>	80A
V <sub>F</sub>	0.85V
T <sub>J</sub> max.	150 °C

### MECHANICAL DATA

**Case:** DO-214AA, molded epoxy body , Epoxy meets UL 94V-0 flammability rating

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD22B-106

**Polarity:** Laser Band Denotes Cathode Band

MAXIMUM RATINGS (TA = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	SK3C0B	UNIT
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	200	V
Maximum RMS voltage	V <sub>RMS</sub>	140	V
Maximum DC blocking voltage	V <sub>DC</sub>	200	V
Maximum average forward rectified current at TL (See Fig.1)	I <sub>F(AV)</sub>	3	A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	80	A
Operating junction temperature range	T <sub>J</sub>	- 55 to + 150	°C
Storage temperature range	T <sub>stg</sub>	- 55 to + 150	°C



# SK3C0B

## ELECTRICAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

PARAMETER	TEST CONDITIONS	SYMBOL	SK3C0B	UNIT
Maximum instantaneous forward voltage	IF=0.5A IF=1 A IF=2 A IF=3A	V <sub>F</sub>	0.7 0.75 0.8 0.85	V
Maximum DC reverse current at rated DC blocking voltage	TA=25	I <sub>R</sub>	100	uA
	TA=125		500	
Typical junction capacitance	4.0 V, 1 MHz	C <sub>J</sub>	68	pF

## THERMAL CHARACTERISTICS (TA = 25 °C unless otherwise noted)

PARAMETER	SYMBOL	SK3C0B	UNIT
Typical thermal resistance	R <sub>θJA</sub> (1)	90	°C/W
	R <sub>θJT</sub> (2)	30	

Notes: (1) Thermal resistance from junction to ambient,  $0.315 \times 0.315"$  ( $8.0 \times 8.0\text{mm}$ ) copper pads to each terminal  
(2) Thermal resistance from junction to terminal,  $0.315 \times 0.315"$  ( $8.0 \times 8.0\text{mm}$ ) copper pads to each terminal

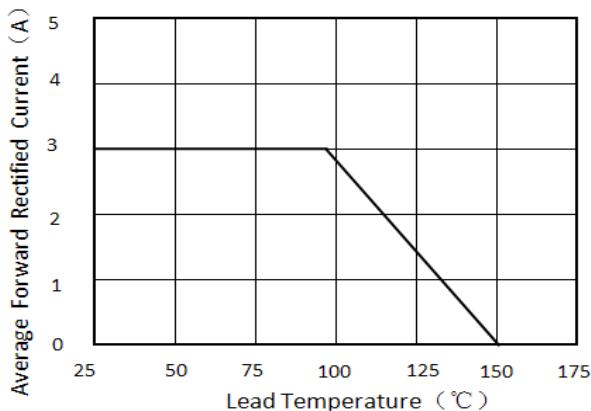


Figure 1. Forward Current Derating Curve

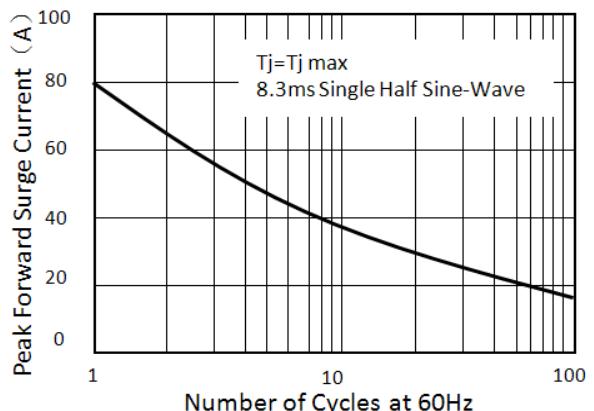


Figure 2. Maximum Non-repetitive Peak Forward Surge Current

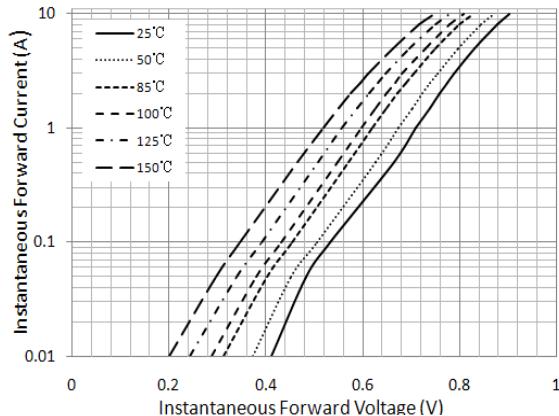


Figure 3. Typical Instantaneous Forward Characteristics

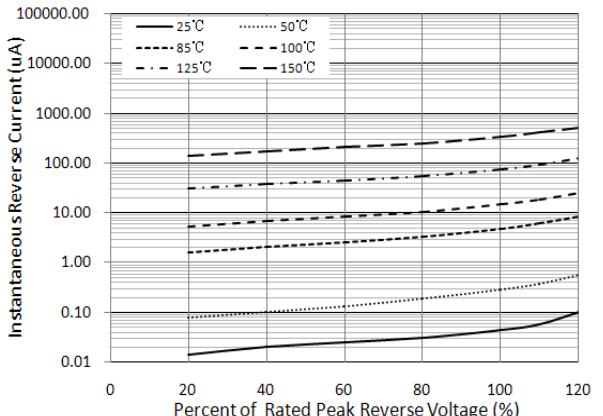
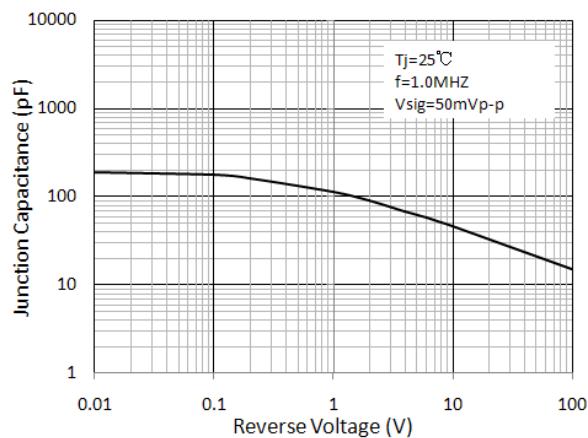


Figure 4. Typical Reverse Characteristics



**Figure 5. Typical Junction Capacitance**

**PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

